

PRODUCT DATA SHEET

Sikafloor®-167 Primer

Epoxy based primer

DESCRIPTION

Sikafloor®-167 Primer is a 2-part, low viscosity, multipurpose epoxy resin which can be used as a primer for levelling mortar, under layer screed, self-smoothing topping.

USES

Sikafloor®-167 Primer may only be used by experienced professionals.

- Primer for concrete substrates, cement screeds and epoxy mortars
- Primer for normal to strongly absorbent surfaces
- Primer for Sika® epoxy and polyurethane flooring systems

CHARACTERISTICS / ADVANTAGES

- Low viscosity
- Good penetration
- Good bond strength
- Easy application
- Short waiting times
- Multi-purpose
- Compatible with subsequent epoxy and polyurethane top coats

PRODUCT INFORMATION

Chemical base	Epoxy	
Packaging	Part A+B pre-batched	6 kg set
	Part A	4 kg container
	Part B	2 kg container
Appearance / Colour	Part A+B mixed	Liquid, brownish-translucent
	Part A (Resin)	Liquid, brownish-transparent
	Part B (Hardener)	Liquid, transparent
Shelf life	12 months from date of production	
Storage conditions	The product must be stored in original, unopened and undamaged sealed packaging in dry conditions at temperatures between +10 °C and +30 °C.	
Density	~1.0 kg/L (+27 °C)	(EN ISO 2811-1)

TECHNICAL INFORMATION

Shore D hardness	~67 (7 days, +23 °C)	(ASTM D2240)
Tensile adhesion strength	≥ 1.5 N/mm ² (concrete failure)	(EN 1542)

APPLICATION INFORMATION

Mixing ratio	Part A : Part B = 2 : 1 (by weight)	
Consumption	0.20–0.30 kg/m ² Note: These figures are theoretical and do not allow for any additional material required due to surface porosity, surface profile, variations in level or wastage etc.	
Ambient air temperature	+8 °C min. / +30 °C max.	
Relative air humidity	80 % max.	
Dew point	Beware of condensation. The substrate and uncured floor must be at least +3 °C above dew point to reduce the risk of condensation or blooming on the floor finish. Low temperatures and high humidity conditions increase the probability of blooming.	
Substrate temperature	+8 °C min. / +30 °C max.	
Substrate moisture content	≤ 4 % parts by weight The following test methods can be used: Sika®-Tramex meter, CM-measurement or Oven-dry-method. No rising moisture according to ASTM (Polyethylene-sheet).	
Pot life	Temperature	Pot life
	+10 °C	50 minutes
	+20 °C	40 minutes
	+30 °C	30 minutes
Times are approximate and will be affected by changing ambient conditions particularly temperature and relative humidity		
Waiting time / Overcoating	Before applying solvent free products on Sikafloor®-167 Primer allow:	
	Substrate temperature	Minimum Maximum
	+10 °C	24 h 4 d
	+20 °C	12 h 2 d
	+30 °C	8 h 1 d
	Times are approximate and will be affected by changing ambient conditions particularly temperature and relative humidity	

BASIS OF PRODUCT DATA

All technical data stated in this Product Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

FURTHER DOCUMENTS

- Sika Method Statement: Evaluation and Preparation of Surfaces for Flooring Systems
- Sika Method Statement: Mixing & Application of Flooring Systems
- Product Data Sheet of subsequent coatings to be applied

ECOLOGY, HEALTH AND SAFETY

User must read the most recent corresponding Safety Data Sheets (SDS) before using any products. The SDS provides information and advice on the safe handling, storage and disposal of chemical products and contains physical, ecological, toxicological and other

safety-related data.

APPLICATION INSTRUCTIONS

IMPORTANT

Strictly follow installation procedures

Strictly follow installation procedures as defined in Method Statements, application manuals and working instructions which must always be adjusted to the actual site conditions.

EQUIPMENT

Mixing

- Electric double paddle mixer (> 700 W, 300 to 400 rpm)

Application

- Squeegee
- Fleece roller
- Brush

SUBSTRATE QUALITY

- Cementitious substrates (concrete / screed) must be structurally sound and of sufficient compressive strength (minimum 25 N/mm²) with a minimum pull off strength of 1.5 N/mm².
- Substrates must be clean, dry and free of all contaminants such as dirt, oil, grease, coatings, laitance, surface treatments and loose friable material.

SUBSTRATE PREPARATION

IMPORTANT

Exposing blow holes and voids

When mechanically preparing the surface, make sure to fully expose blow holes and voids.

Mechanical substrate preparation

- Remove weak cementitious substrates.
- Prepare cementitious substrates mechanically using abrasive blast cleaning or planing / scarifying equipment to remove cement laitance and achieve an open textured surface gripping surface profile suitable for the product thickness.
- Before applying thin layer resins, remove high spots by grinding.
- Use industrial vacuuming equipment or brush to remove all dust, loose and friable material from the application surface before applying the Product.
- Use products from the Sikafloor®, Sikadur® and Sikagard® range of materials to level the surface or fill cracks, blow holes and voids.

Contact Sika Technical Services for additional information on products for levelling and repairing defects.

Substrate preparation of non-cementitious substrates

For information on substrate preparation of non-cementitious substrates, contact Sika Technical Services.

Treatment of joints and cracks

Construction joints and existing static surface cracks in substrate require pre-treating before full layer application. Use Sikadur® or Sikafloor® resins.

IMPORTANT

Incorrect treatment of cracks

The incorrect assessment and treatment of cracks may lead to a reduced service life and reflective cracking.

MIXING

1. Mix Part A (resin) for ~30 seconds.
2. Add Part B (hardener) to Part A.
3. Mix continuously for 3 minutes, until a uniform mix is achieved.
Note: Avoid excessive mixing to minimise air entrainment.

4. To increase the viscosity of the product, add Sika® Extender T in defined quantity.
5. To ensure thorough mixing, pour materials into another container and mix again to achieve a smooth and uniform mix.
6. During the final mixing stage, scrape down the sides and bottom of the mixing container with a flat or straight edge trowel at least once to ensure complete mixing. Mix full units only.

APPLICATION

IMPORTANT

Usage of aggregates

Any aggregate used with Sikafloor® systems must be non-reactive and oven-dried. For best results, use Sika aggregates.

IMPORTANT

Application in high moisture

If > 4 % pbw moisture content, Sikafloor® EpoCem® may be applied as a T.M.B. (temporary moisture barrier) system.

IMPORTANT

Protect from moisture

After application, protect the product from damp, condensation and direct water contact for at least 24 hours.

IMPORTANT

Temporary heating

If temporary heating is required, do not use gas, oil, paraffin or other fossil fuel heaters. These produce large quantities of both carbon dioxide and water vapour, which may adversely affect the finish.

1. For heating, use only electric powered warm air blower systems.

IMPORTANT

Pin holes

If applied on porous substrates during rising temperatures pin holes may occur from rising air.

1. Apply during falling temperatures.

IMPORTANT

Closing Pin holes

If pin holes are present after the product has cured, they can be closed by doing the following.

1. Lightly grind the cured surface.
2. Apply a scratch coat consisting of the product mixed with ~3 % of Sika® Extender T.

Standard primer application

1. Pour the mixed product onto the substrate. The consumption is specified in Application Information.

2. Apply the product evenly over the surface with brush, fleece roller or squeegee.
3. Back roll the surface in two directions at right angles with a fleece roller. Maintain a "wet edge" during application to achieve a seamless finish.
4. Ensure a continuous, pore free coat covers the substrate. If necessary, apply second coat.
5. **(Optional)** If broadcasting is required, wait between 15 and 30 minutes, then broadcast the surface with quartz sand. Broadcast lightly at first, then to excess.
6. **(Optional)** Once the product has hardened sufficiently, remove all loose sand with industrial vacuuming equipment. **IMPORTANT:** Confirm waiting / overcoating time is achieved before applying subsequent products. (Refer to waiting / overcoating times in Application Information)

CLEANING OF TOOLS

Clean all tools and application equipment with Thinner C or suitable solvent immediately after use. Hardened material can only be removed mechanically.

LOCAL RESTRICTIONS

Note that as a result of specific local regulations the declared data and recommended uses for this product may vary from country to country. Consult the local Product Data Sheet for exact product data and uses.

LEGAL NOTES

The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the product's suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

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Product Data Sheet

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